

Basic Agreement with Mitsubishi Materials Corporation about acceptance of assignment of Dicing Blade Business

February 2nd, 2012

Company Name



Tokyo Seimitsu Co., Ltd.

Stock Listing: First Section TSE

ACCRETECH

Code number: 7729

(URL: <http://www.accretech.jp/>)

Representative: Kunimasa Ohta, President

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Tokyo Seimitsu announces the decision of today's Board of Directors' Meeting that the company executes a basic contract with Mitsubishi Materials Corporation with respect to obtaining of their business regarding Dicing Blade Products (*) by accepting assignment of business (*Jigyou Jyouto*). The details are as follows;

1. Background and Purpose of this Assignment of Business

Since many years Tokyo Seimitsu has developed Dicing Machines with advanced technologies and tried to meet every dicing requirement of customers. Nowadays their application requirements are getting more and more complex, intense and diverse.

Under such business circumstances, Tokyo Seimitsu recognizes the importance of support to customers, not only for equipments but also for dicing blades, and has been discussing with Mitsubishi Materials Corporation about the possibility of assignment of their Dicing Blade Business. Lately, Tokyo Seimitsu came to basic agreement with them about the assignment.

By obtaining the technologies and know-hows which Mitsubishi Materials has developed until today, Tokyo Seimitsu will be able to greatly improve its support ability to meet diverse requirements of customers and will develop the business of both equipments and dicing blades.

2. Planned Schedule

On May 30, 2012 (planned) : Entering into the Business Assignment Contract

On July 1, 2012 (planned) : Effective Day of the Assignment of Business

3. General information about the contract partner "Mitsubishi Materials Corporation"

Address : Otemachi 1-3-2, Chiyoda-ku, Tokyo

Representative : Mr. Hiroshi Yao / President

Capital : ¥119,457 million (as of end of March, 2011)

Main business : Cement, Metals, Advanced Materials & Tools, Aluminium, Electronic Materials & Components, Energy, Precious Metals and Recycling business

4. Influence on the Company's Results

Influence on the company's results is very limited by this acceptance of assignment of the business.

(*) Dicing Blade Products : precision cutting blades using industrial diamonds, which cut semiconductor chips and electronic devices like ceramic condensor, LED package, and various IC packages mainly built in consumer electric products